



Nov 15, 2022





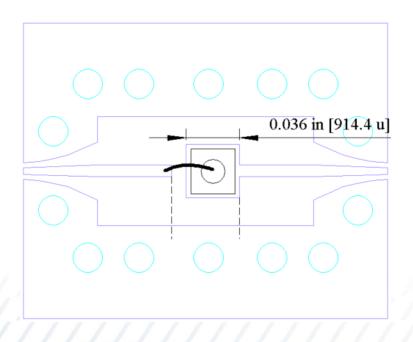
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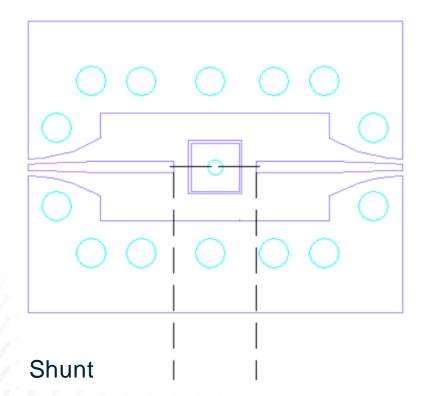


#### **Test Fixtures**

- 10 mils Rogers RO3010 with 1/2 oz copper
- S-parameters measured with port extensions such that the reference planes are set to the dash lines on the input and output as shown below

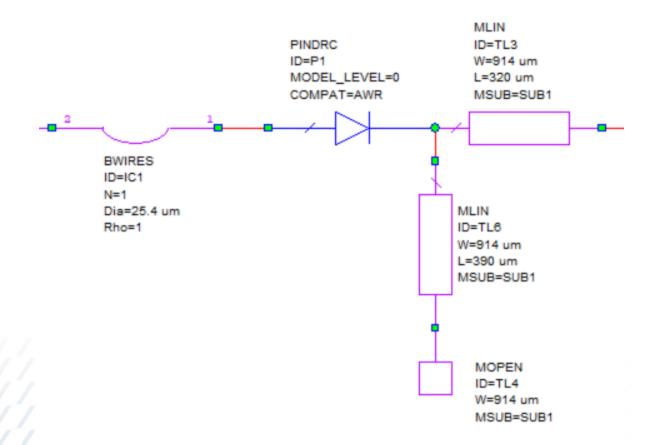


Series



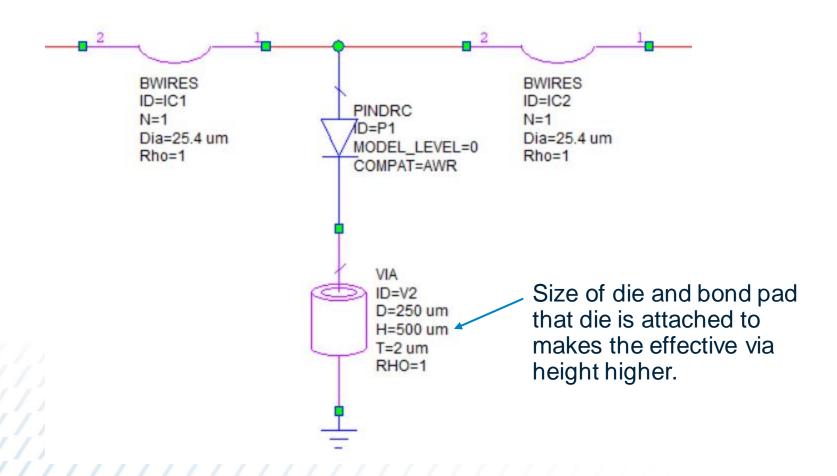


## **Series Test Fixture Model**



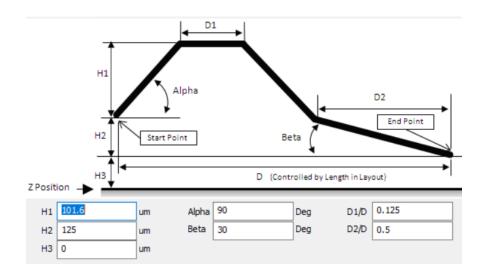


#### **Shunt Test Fixture Model**





# **Bond Wire**



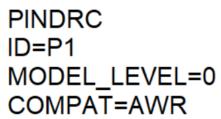
Element Options: BWIRES - Bond wire model (EIA/JEDEC Standard No. 59)

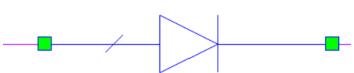
Bondwire Pro	file Parameters	User At	tributes	Symbol	Layout Mo	del Option		
▼ 2 <sup>nd</sup> MYield H □								
Name	Value	Unit	Tune	Optimize	Constrain	Lower		
ID	IC1							
N	1							
Dia	25.4	um						
Rho	1							
WModel	4 segments							
Alpha	90	Deg						
Beta	30	Deg						
H1	101.6	um						
H2	125	um						
H3	0	um						
D1_Ratio	0.125							
D2_Ratio	0.5							
P0	{0,0}	um						
P1	{BW_len,0}	um						
IndModel	RLC							

BW\_len = 1110



# **Robert Caverly PIN Diode Model**



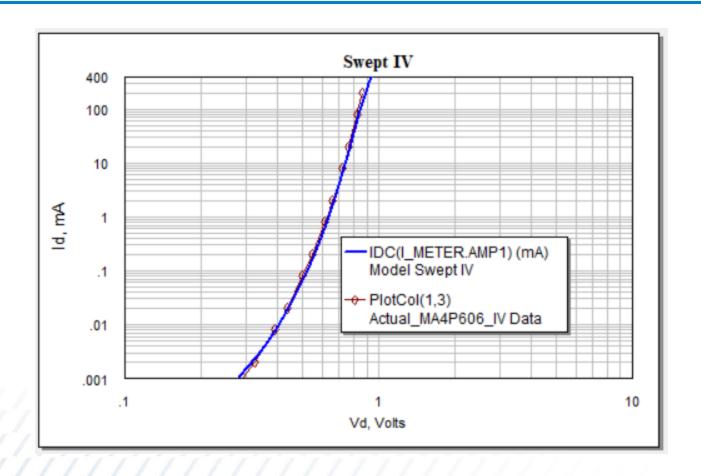


Name	Value	Unit
ID	P1	
IS	Is	mA
IKNEE	Iknee	mA
N	Npin	
RLIM	Rs	Ohm
REPI	Repi	Ohm
CJ	Cj	pF
CPKG	Cpkg	pF
TAU	LT	ns
W	W	
В	3	
LBOND	Lpkg	nH
TNOM	26.85	DegC
TEMP	26.85	DegC
AREA	1	
NFLAG	Noise Off	

Is=4.92e-06 Iknee=7 Npin=1 Repi=1000 LT=5000 W=96 Cj = 0.48Rs=0.05 Cpkg=0.0 Lpkg=0.0

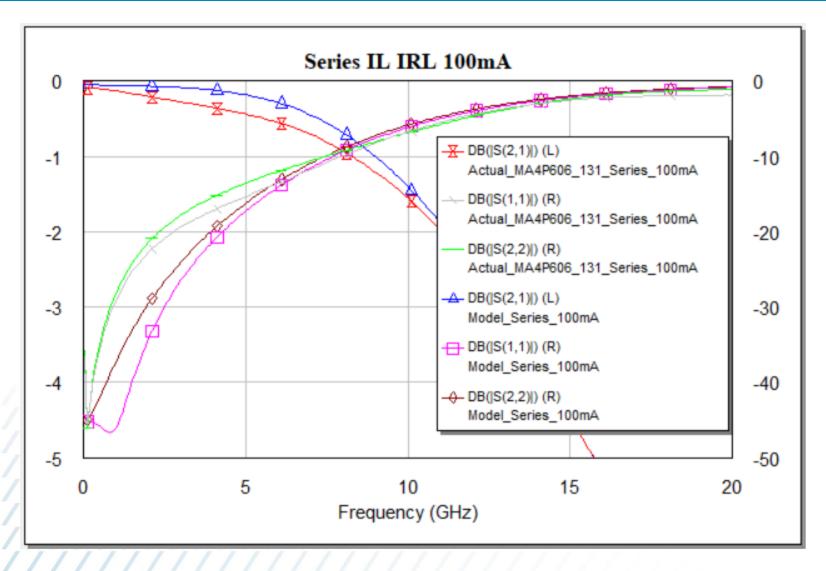


# **IV Curve**



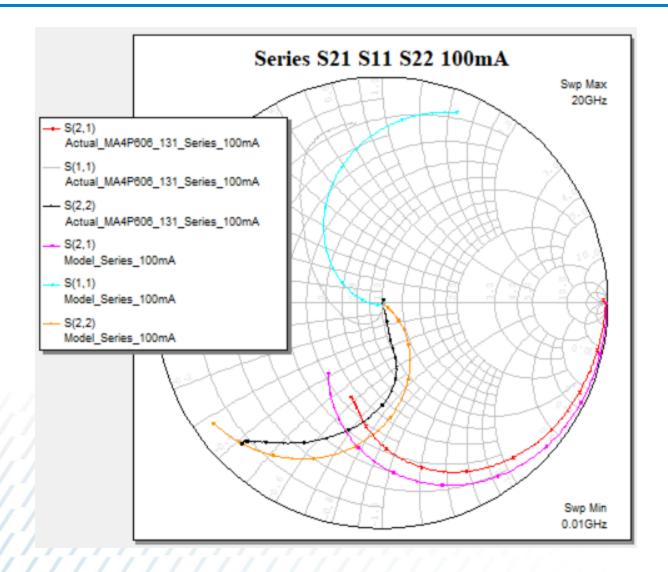


#### Series 100 mA



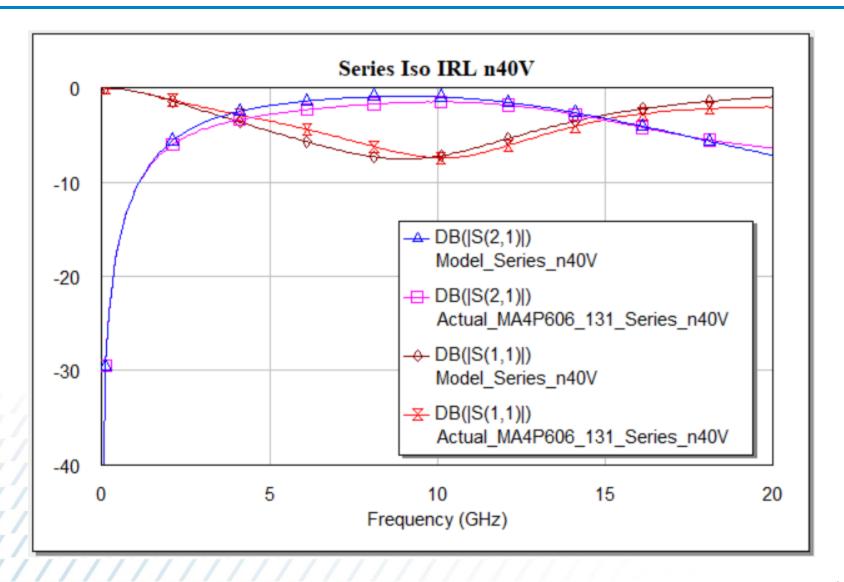


## Series 100 mA



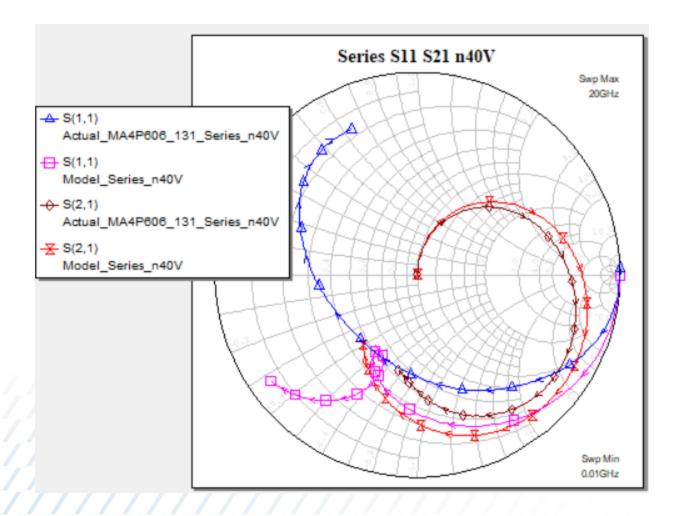


#### Series -40 V



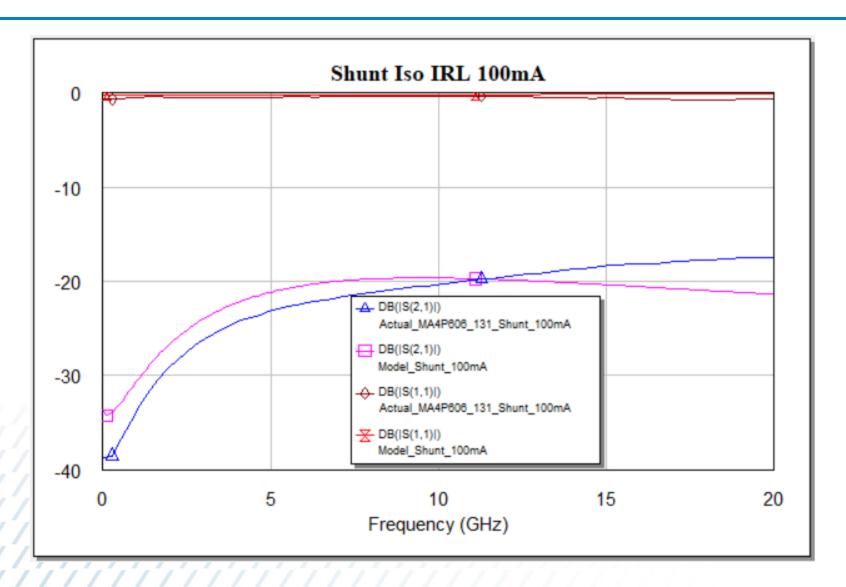


## Series -40 V



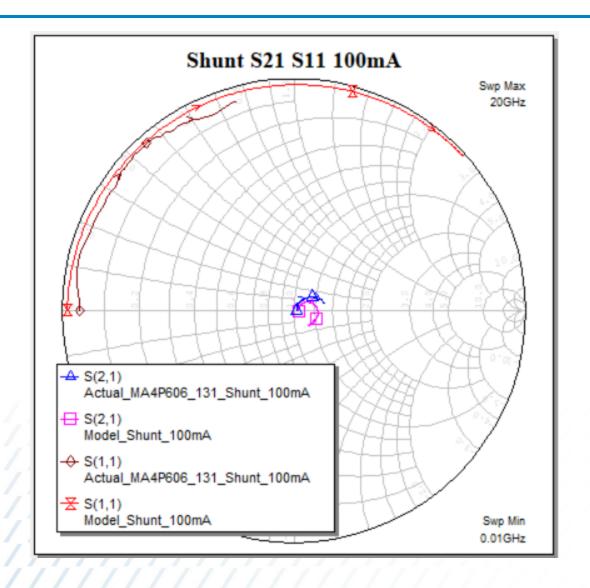
## Shunt 100 mA





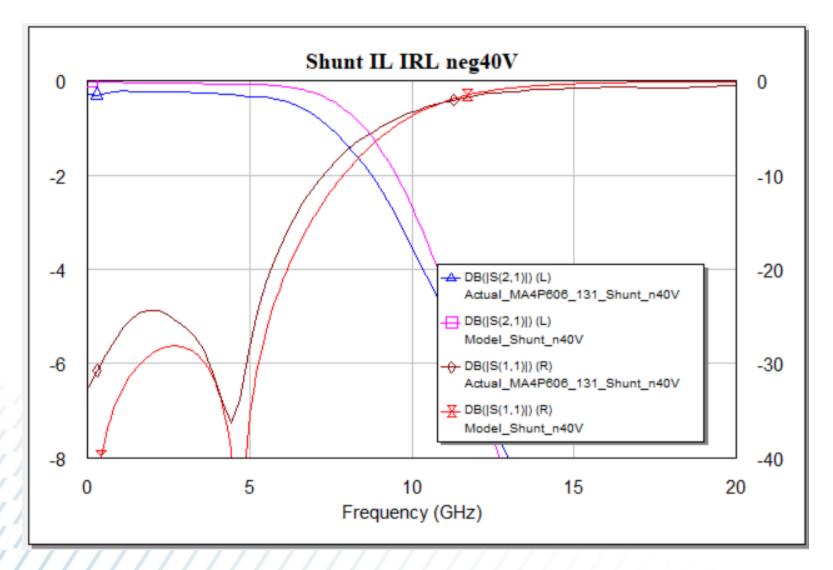
# Shunt 100 mA





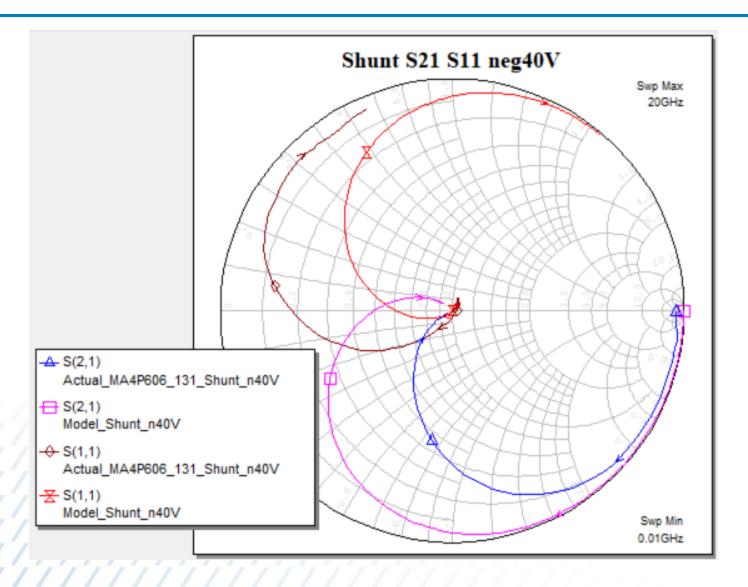
## Shunt -40 V





## Shunt -40 V





#### **Disclosure**



These models are furnished on an "as is" basis without warranty of any kind. MACOM reserves the right to make changes to any model without notice. Although the use of models can be a useful tool in evaluating devices for applications, they do not exactly model all device characteristics under all conditions.